

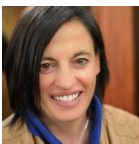
SEMICON® EUROPA

NOV 15-18, 2022 | MUNICH, GERMANY



ITF Beyond 5G

Welcome



K. Marent
EVP & Chief Marketing and Communications
Officer
imec, Brussels, Belgium



Abstract

Coming Soon

Biography

Katrien has an engineering degree in microelectronics. She joined imec in 1992 as analog design engineer and specialized in design of low-noise readout electronics for high-energy physics. In 1999, she became press responsible and scientific editor at imec's business development division and was responsible for authoring and editing the research organization's numerous company technical documents and publications. In 2001, she was appointed corporate communications director at imec. Her responsibilities expanded in August 2007, when she got the position of external communications director including corporate, marketing and outreach communications. In October 2016, she became VP corporate, marketing and outreach communication. Since April 2020 she is Executive Vice President & Chief Marketing and Communications Officer and member of the executive board of imec.

Opening



M. Peeters
VP of R&D for Connectivity
imec, Brussels, Belgium



Abstract

Coming Soon

Biography

Michael Peeters is VP of R&D for Connectivity at imec. His previous experience as CTO for both the Wireline and Wireless business lines at (what is now) Nokia was built on the culture, enthusiasm, and love for technology and science that he got from his time at Bell Labs—and the principles of Free Inquiry bestowed on him by his Alma Mater, the Vrije Universiteit Brussel (VUB).

During his research career starting with a Ph.D. in Applied Physics and Photonics from the Vrije Universiteit Brussel, he has authored more than 100 peer-reviewed publications, many white papers and holds patents in the access and photonics domains. An electrotechnical engineer by training, he is a senior member of IEEE and a Fellow of the VUB.

Outside of work, his quest to discover the recipe for a perfect lasagna is balanced by bouts of long-distance running to offset the inherent caloric intake.

Industry talk



C. Maleville
CTO, Executive VP Innovation Organization
Soitec, Bernec, France



Abstract

Coming Soon

Biography

Christophe Maleville has been appointed senior vice president of Soitec's Innovation.

He joined Soitec in 1993 and was a driving force behind the company's joint research activities with CEA-Leti. For several years, he led new SOI process development, oversaw SOI technology transfer from R&D to production, and managed customer certifications. He also served as vice president, SOI Products Platform at Soitec, working closely with key customers worldwide.

Maleville has authored or co-authored more than 30 papers and also holds some 30 patents. He has a PhD in microelectronics from Grenoble Institute of Technology and obtained an executive MBA from INSEAD.

Industry talk



G. U'Ren
Director RF Technologies
X-FAB Group, Dresden, Germany



Abstract

Coming Soon

Biography

Dr. Gregory U'Ren is the Director of RF Technologies at X-FAB responsible for incubating and subsequently delivering integrated device technology solutions including reference designs and foundational design IP. During his career, he has held both leadership and individual roles contributing to the advancement of a broad range of specialty technologies including SiGe BiCMOS, RF-SOI, MEMS, and GaN. Current activities are focused on the RF front end for 5G or 6G systems engaging various collaborations with academic and industrial partners on a wide range of topics including materials, process, RF/mmW characterization, advanced modeling, and EDA tooling enhancements to support several program initiatives at X-FAB.

He is a senior member of IEEE, a member of the American Physics Society, and holds over 30 patents. He completed his PhD and MS at the University of California Los Angeles.

Tech talk



N. Collaert
Program Director High-Speed Analog/RF
imec, Brussels, Belgium



Abstract

Coming Soon

Biography

Dr. Nadine Collaert is program director at imec. She is currently responsible for the analog/RF program looking at heterogeneous integration of III-V/III-N devices with advanced CMOS to tackle the challenges of next generation mobile communication. Before that she was program director of the LOGIC Beyond Si program focused on the research on novel CMOS devices and new material-enabled device and system approaches to increase functionality. She has been involved in the theory, design, and technology of FinFET devices, emerging memories, transducers for biomedical applications and the integration and characterization of biocompatible materials. She has a PhD in electrical engineering from the KU Leuven and she holds more than 400 publications and more than 10 patents in the field of device design and process technology.

Industry Talk: THz Frequencies and Mobile Networks – a good blend?

F. Tillman
Head of Integrated Radio Systems
Ericsson Research, Brussels, Denmark



ERICSSON

Abstract

Coming Soon

Biography

Fredrik Tillman received the Msc and PhD degrees in Circuit Design from Lund University in 2000 and 2005 respectively. After graduation he joined Ericsson Mobile Platforms and participated in the first cellular modem CMOS radio development before moving on to the research branch of the company. Today Fredrik is heading a department at Ericsson Research with focus on integrated radio circuit design for both cellular infrastructure and device connectivity. Besides being responsible for internal R&D activities, Fredrik is active in the European research community and has been the Ericsson driver for multiple collaboration projects within the Horizon 2020 framework.

How Advanced Epitaxy is Critical to making the Semiconductors for Next-Gen Mobile Connectivity

R. Pelzel
CTO
IQE, Dresden, Germany



Abstract

The epitaxy process is the most critical and demanding step in the RF semiconductor manufacturing chain. In this presentation, we'll discuss the role of advanced epitaxy for RF to 5G and beyond, including higher frequencies up to 300 MHz, and highlight different materials (III-V, silicon, and germanium). We'll look at how IQE sees the market trends and needs, which applications are the most demanding, and how IQE is innovating – for example, how the development of InP epiwafer HBT and HEMT structures has enabled our customers to develop transceiver chipsets with world-class performance. We'll look ahead at how IQE sees its role in the future ecosystem, what are the biggest challenges, and where technology innovation in epitaxy will take us.

Biography

Dr. Rodney Pelzel has over 20 years of experience in the semiconductor industry, with deep expertise in semiconductor materials engineering and the epitaxial growth of compound semiconductors. Dr. Pelzel joined IQE as a Production Engineer in 2000. For the first twelve years of his career with IQE, Dr. Pelzel held various engineering and operational management roles focusing on scaling leading-edge epitaxial technology for volume manufacturing for wireless applications. In 2012, Dr. Pelzel was appointed as the head of R&D for the IQE Group and was tasked with creating unique materials solutions that enable IQE's customers and provide them with a competitive edge. Throughout his career, Dr. Pelzel has been involved in numerous new product introductions, the most recent being IQE's highly successful launch of 6" VCSELs for consumer applications. Dr. Pelzel is a chemical engineer by training, holding a BS (High Distinction) from the University of Colorado (1995) and a Ph.D. from the University of California, Santa Barbara (2000). He is a Chartered Engineer and a Chartered Scientist, and a Fellow of the Institution of Chemical Engineers. Dr. Pelzel's work has been widely published and he is the co-inventor of 30+ patents.



M. Peeters
VP of R&D for Connectivity
imec, Brussels, Belgium



Biography

Michael Peeters is VP of R&D for Connectivity at imec. His previous experience as CTO for both the Wireline and Wireless business lines at (what is now) Nokia was built on the culture, enthusiasm, and love for technology and science that he got from his time at Bell Labs—and the principles of Free Inquiry bestowed on him by his Alma Mater, the Vrije Universiteit Brussel (VUB).

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and a Fellow of the VUB.

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Panelist



V. Ziegler
Senior Technology Advisor & Chief Architect
Nokia, Helsinki, Finland

NOKIA

Abstract

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Biography

Volker is an energetic leader with 25+ years of broad and international experience in the telecommunications industry. He currently serves as Senior Technology Advisor and Chief Architect in Nokia Strategy and Technology unit. Previously, Volker has exercised a leadership role with Nokia Bell Labs in 6G research and ecosystem and has served as Head of 5G Leadership and Chief Architect of Nokia Mobile Networks. Prior to this, Volker has been active in the Head of Strategy role of Nokia Siemens Networks where he had also served as the Head of the North East Region. In his 10+ year career with Siemens, Volker has held business unit leadership, finance, sales and marketing, services and R&D global roles and senior positions. He has worked as Information Technology Specialist with the World Bank / IFC in the mid-90s. Volker has started his career as a research scientist with German Aerospace Research / DLR. Volker holds a Dr.-Ing. (PhD) degree in Electrical Engineering from Technische Hochschule (TH) Karlsruhe in Germany and is a graduate of the Executive Development Program at Harvard Business School.

Panelist



M. Alexander
Partner Advanced Technology Center Industrial
Platform
Roland Berger, Brussels, Belgium



Abstract

Not applicable

Biography

Dr. Michael Alexander joined Roland Berger in 2014 as a Partner in our Industrial platform. He is an industry expert in the electronics and semiconductor business and founded Roland Berger's Advanced Technology Center. His recent consulting work has centered on strategy, business development and R&D management, with a special focus on electronic component industries. He has carried out successful projects for international electronics, semiconductor, renewables and machinery groups in Europe, Japan, Southeast Asia and the US.

Michael brings more than 15 years of management experience in Europe and Asia to Roland Berger. He holds several Advisory Board seats in the B2B industry and science community. He also spent five years with another large international consultancy.

Prior to his work in industry and consulting, he pursued an academic career at the Max-Planck-Institute of Solid State Research and as a Post-Doc at the Industrial Research Institute (IRI) in Yokohama, Japan. In 1991, he received the "Young Scientist Award" from the Werner-von-Siemens-Ring Foundation. Michael holds a Master's degree in Physics from the University of Munich (LMU) and a PhD from the University of Stuttgart in Semiconductor Physics. Prior to his academic education he also received vocational training in banking.

Panelist



R. Stuhlfauth
Technology Manager Wireless
Rohde & Schwarz, Dresden, Germany



Abstract

Not applicable

Biography

Reiner Stuhlfauth is a technology manager wireless from the Test & Measurement Division of Rohde & Schwarz in Munich. Before that he worked as trainer and has more than 20 years experience in teaching and promoting mobile communication technologies in the background of cellular standards and non-cellular technologies. He is involved in several projects concerning 5G, 5G advanced and 6G research activities. Reiner has published several technical documents, webinars and he is one of the authors of the R&S technology book "5G New Radio – fundamentals, procedures, testing aspects". He holds the academic degree of engineer in telecommunications (Dipl.-Ing) issued by the Technical University of Kaiserslautern.